

ABSTRACT

RESIN PASTE FOR DIE BONDING AND ITS USE

- 5 Disclosed is a resin paste for die bonding comprising a carboxylic acid-terminated butadiene homopolymer or copolymer (A), a thermosetting resin (B), a filler (C), and a solvent (D) for printing. This resin paste has a modulus of elasticity of 1 to 100 MPa (25°C) after dry curing. Preferably, the resin paste has a solid content of 40 to 90% by weight, a thixotropy index of 1.5 to 8.0, and a viscosity (25°C) of 5 to 1000 Pas. A
- 10 semiconductor device is produced using the resin paste by a method comprising (1) coating a predetermined amount of the resin paste onto a substrate, (2) drying the resin paste to bring the resin to B-stage, (3) mounting a semiconductor chip onto the B-stage resin, and (4) post-curing the resin.